

SOT1908-1

FBGA448, fine-pitch ball grid array package, 448 terminals,
0.75 mm pitch, 17 mm x 17 mm x 2.46 mm body

28 June 2019

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	FBGA448
Package style descriptive code	FBGA (fine-pitch ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	04-06-2019
Manufacturer package code	98ASA01058D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	17	-	mm
package width	-	17	-	mm
seated height	-	2.46	-	mm
nominal pitch	-	0.75	-	mm
actual quantity of termination	-	448	-	



FBGA448, fine-pitch ball grid array package, 448 terminals, 0.75 mm pitch, 17 mm x 17 mm x 2.46 mm body

2 Package outline

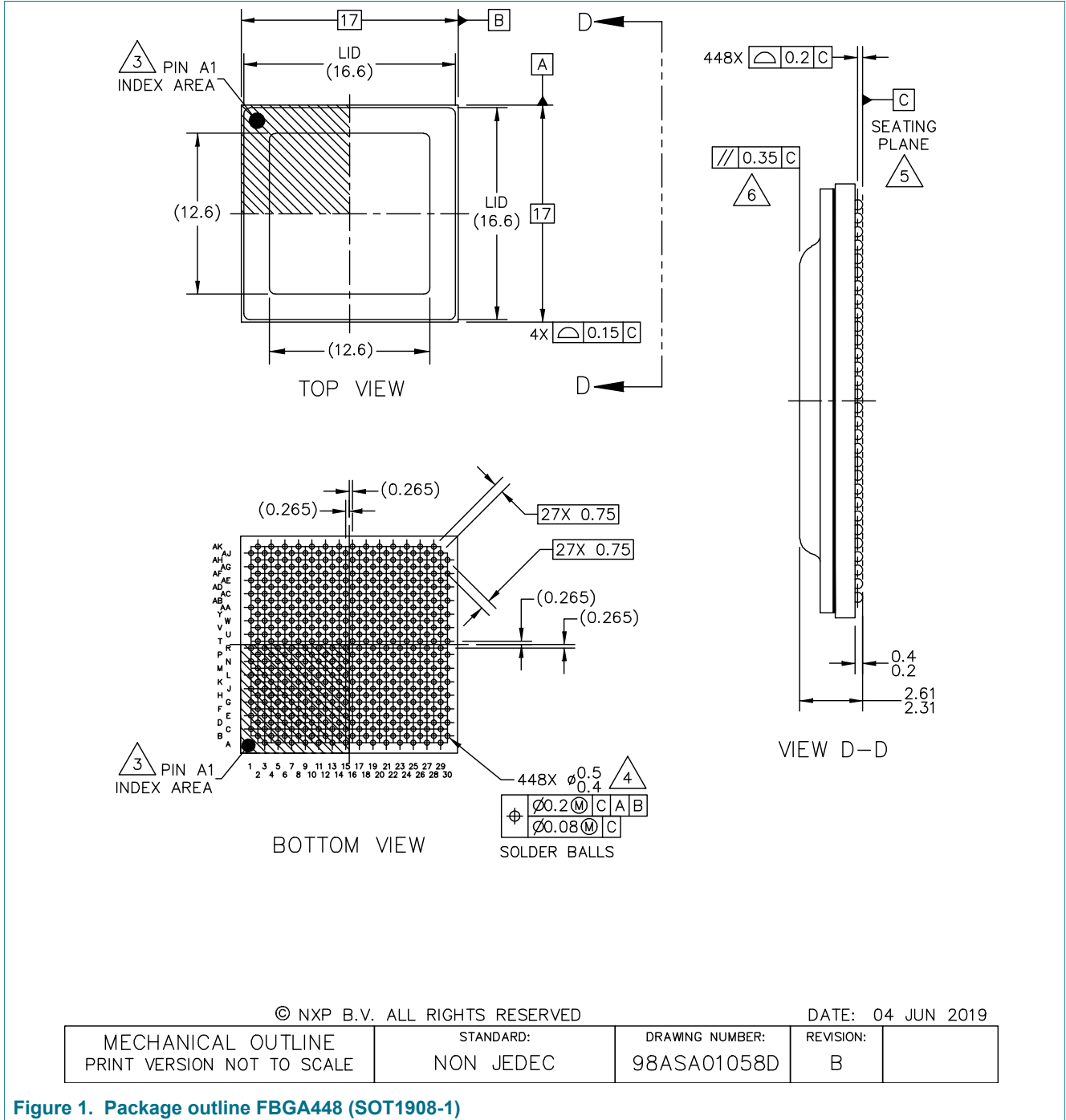
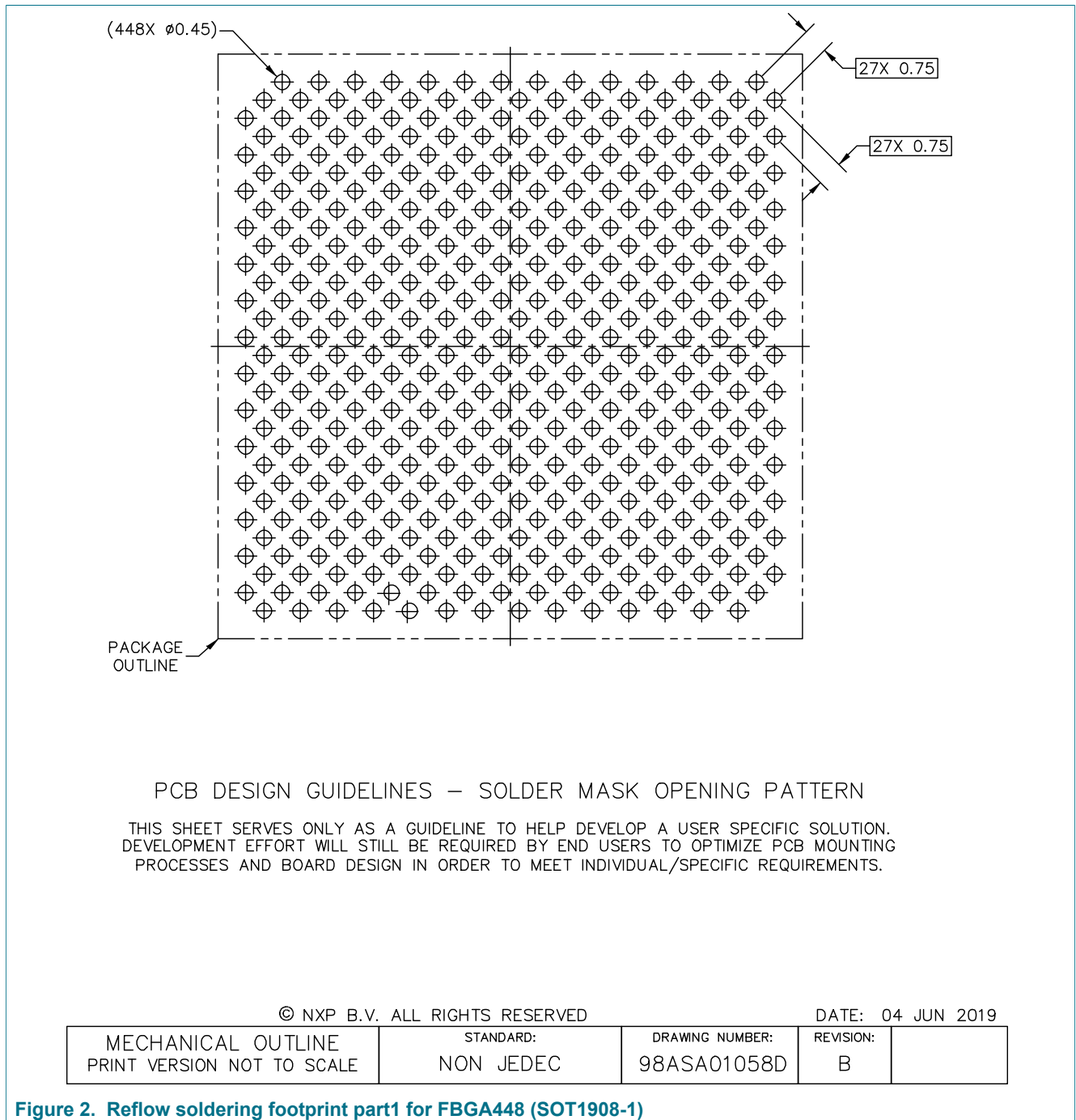
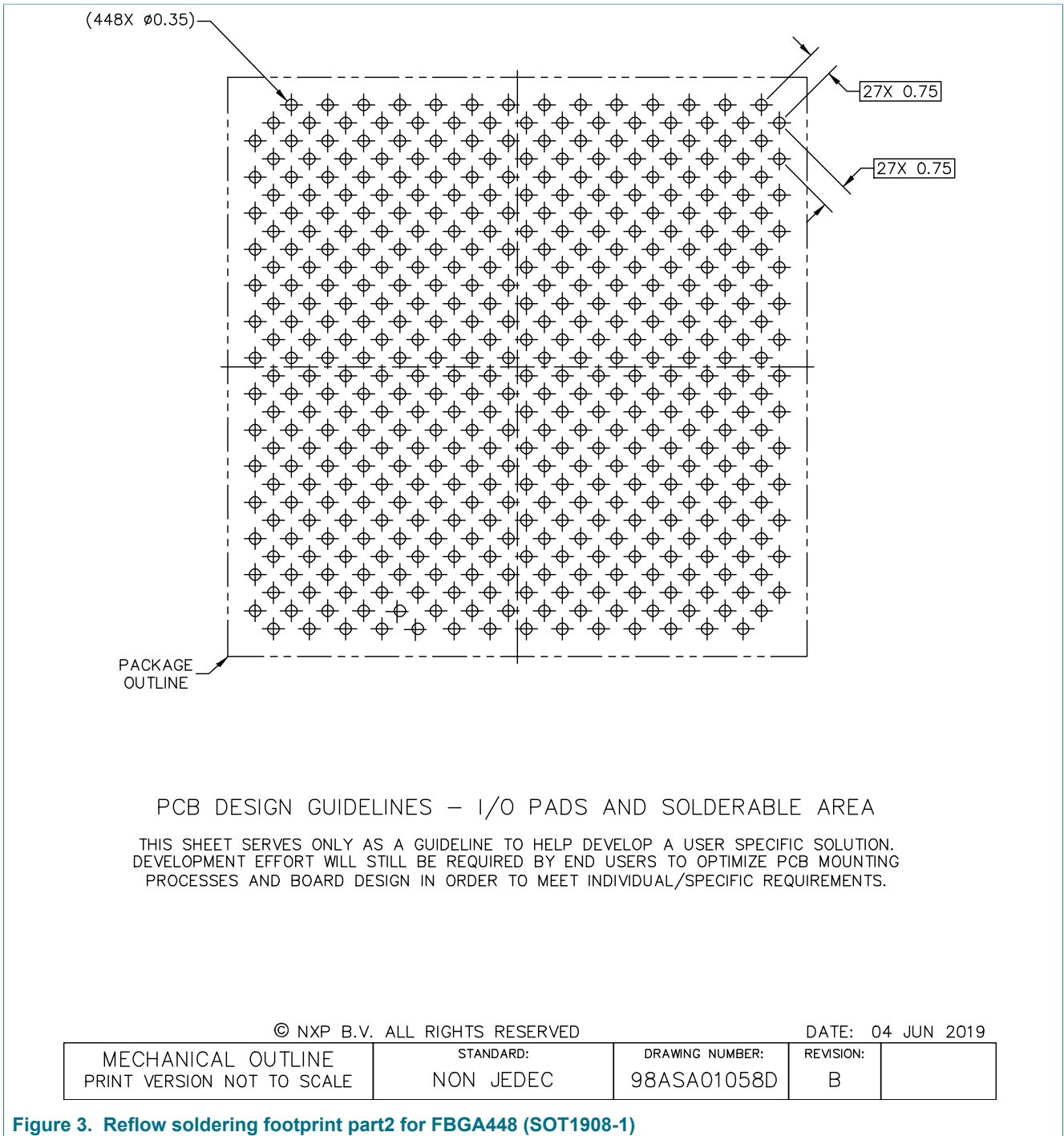


Figure 1. Package outline FBGA448 (SOT1908-1)

3 Soldering





FBGA448, fine-pitch ball grid array package, 448 terminals, 0.75 mm pitch, 17 mm x 17 mm x 2.46 mm body

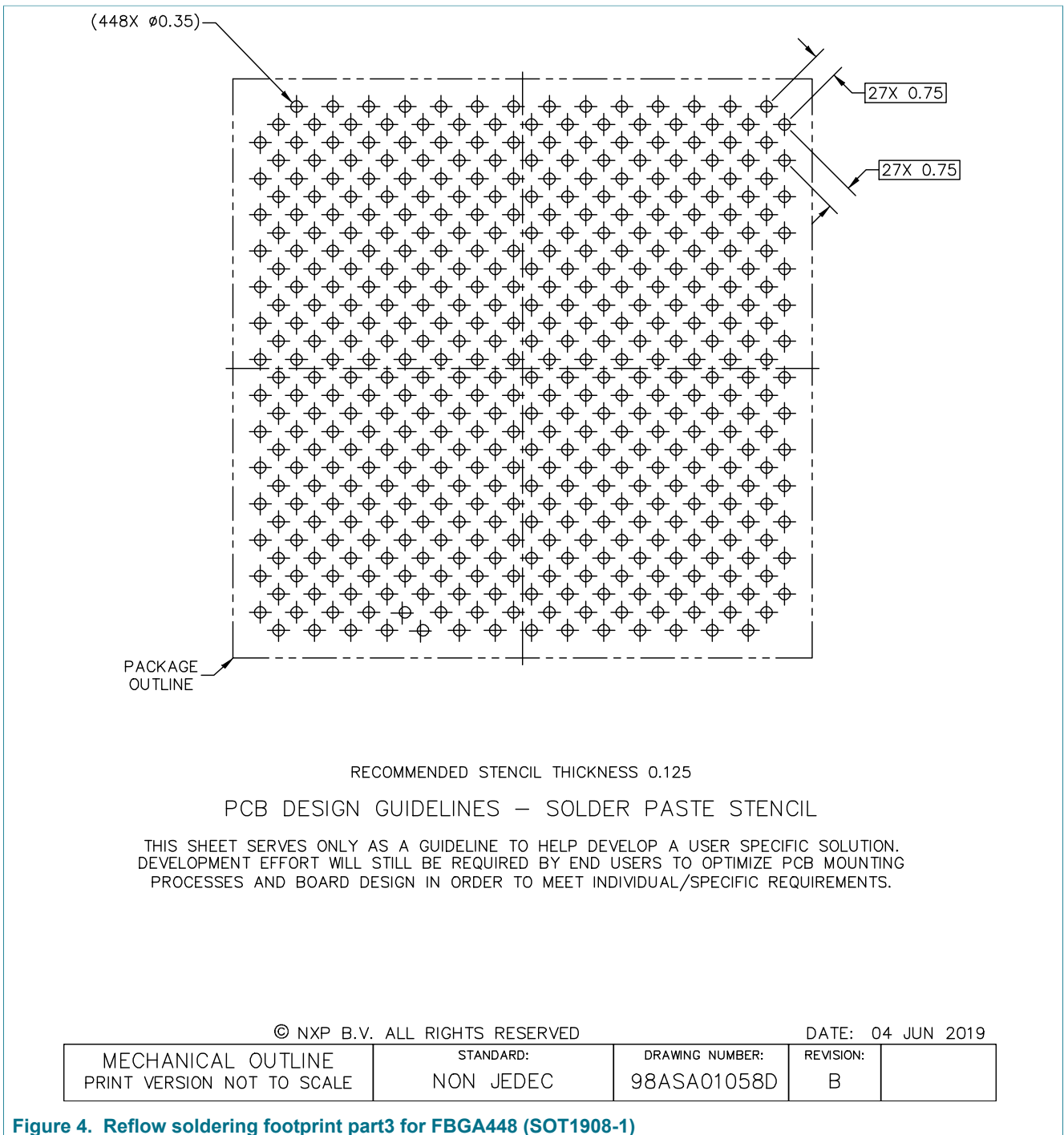


Figure 4. Reflow soldering footprint part3 for FBGA448 (SOT1908-1)

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NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.
7. LID OVERHANG ON SUBSTRATE NOT ALLOWED.

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DATE: 04 JUN 2019

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01058D	REVISION: B	
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Figure 5. Package outline note FBGA448 (SOT1908-1)

4 Legal information

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